

ABSTRACT

The present invention provides an electrically conductive resin composition capable of giving a cured product superior in bond strength and electric conductivity even through curing at low temperature such as about 80°C. An electrically conductive resin composition containing components (A) to (C), wherein the component (C) contains (C-1) and (C-2), and the component (A) is an epoxy resin, the component (B) is an electrically conductive particle, the component (C) is a polyamine-based latent curing agent, the (C-1) is a polyamine-based latent curing agent having a softening point of 50 to 129°C, and the (C-2) is a polyamine-based latent curing agent having a softening point of 130 to 180°C.

No figure.